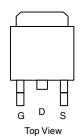


Vishay Siliconix

P-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)			
- 60	0.019 at V _{GS} = - 10 V	- 55	76			
	0.025 at V _{GS} = - 4.5 V	- 48	70			

TO-263

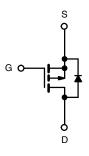


Ordering Information: SUM55P06-19L-E3 (Lead (Pb)-free)

FEATURES

- TrenchFET[®] Power MOSFET
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	- 60	v			
Gate-Source Voltage	V _{GS}	± 20	- V			
Continuous Drain Current ^d (T 175 °C)	T _C = 25 °C	Ι _D	- 55			
Continuous Drain Current ^d (T _J = 175 °C)	T _C = 125 °C		- 31			
Pulsed Drain Current	I _{DM}	- 150	- A			
Avalanche Current		I _{AS}	- 45			
Single Pulse Avalanche Energy ^a	L = 0.1 mH	E _{AS}	101	mJ		
Devery Dissignation	$T_{C} = 25 \text{ °C}$ $T_{A} = 25 \text{ °C}^{b}$	Р	125 ^c	10/		
Power Dissipation	T _A = 25 °C ^b	P _D	3.75	W		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount ^b	R _{thJA}	40	°C/W		
Junction-to-Case		R _{thJC}	1.2	0/11		

Notes:

a. Duty cycle $\leq 1\%$.

b. When mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

d. Limited by package.

SUM55P06-19L

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		· · · ·					
Drain-Source Breakdown Voltage	V _{DS}	V_{GS} = 0 V, I _D = - 250 µA	- 60			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 1		- 3	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	- 1		- 1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50		
		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 175 °C			- 250	1	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.015	0.019		
	Б	V_{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C			0.033		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C			0.041	Ω	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.020	0.025	1	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 50 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			3500		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V, V_{DS} = -25 V, f = 1 MHz$		390			
Reverse Transfer Capacitance	C _{rss}			290			
Total Gate Charge ^c	Qg			76	115	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -55$ A		16			
Gate-Drain Charge ^c	Q _{gd}			19			
Gate Resistance	R _g	f = 1 MHz		5.2		Ω	
Turn-On Delay Time ^c	t _{d(on)}			12	20		
Rise Time ^c	t _r	$V_{DD} = -30 \text{ V}, \text{ R}_{\text{I}} = 0.54 \Omega$		15	25	- ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_{D} \cong -55 \text{ A}, \text{ V}_{\text{GEN}} = -10 \text{ V}, \text{ R}_{\text{g}} = 2.5 \Omega$		80	120		
Fall Time ^c	t _f	- Č		230	350		
Source-Drain Diode Ratings and Cha	· ·	$c = 25 \ ^{\circ}C^{b}$					
Continuous Current	I _S				- 110		
Pulsed Current	I _{SM}				- 240	Α	
Forward Voltage ^a	V _{SD}	I _F = - 50 A, V _{GS} = 0 V		- 1	- 1.5	V	
Reverse Recovery Time	t _{rr}			45	68	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 50 A, di/dt = 100 A/μs		- 2.6	- 4	A	
Reverse Recovery Charge				0.059	0.136	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

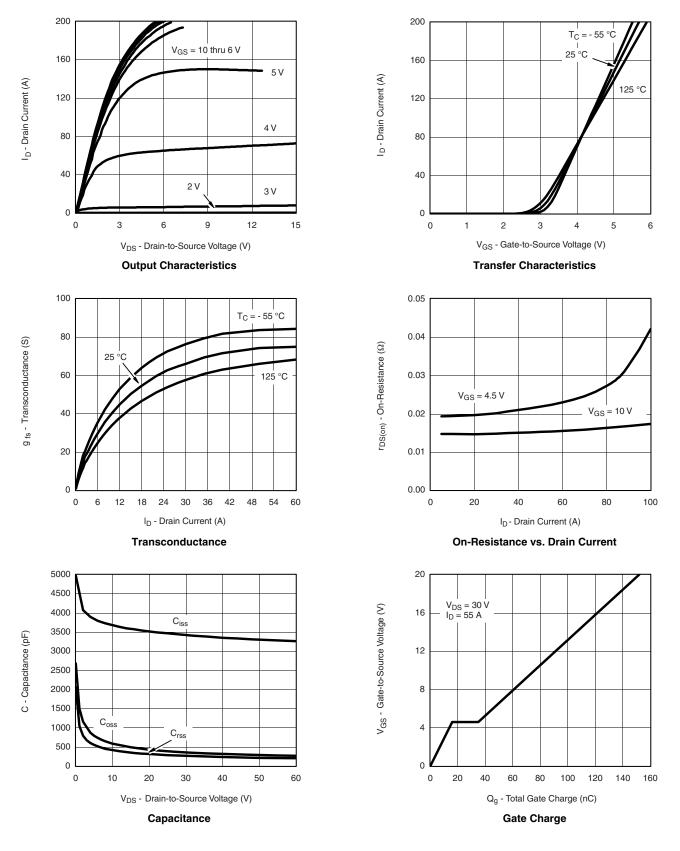
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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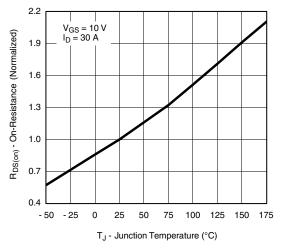
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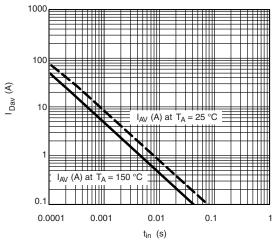


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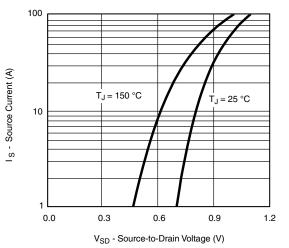
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



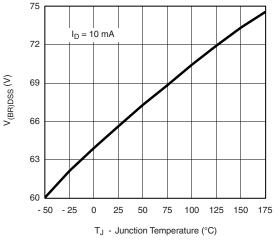
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



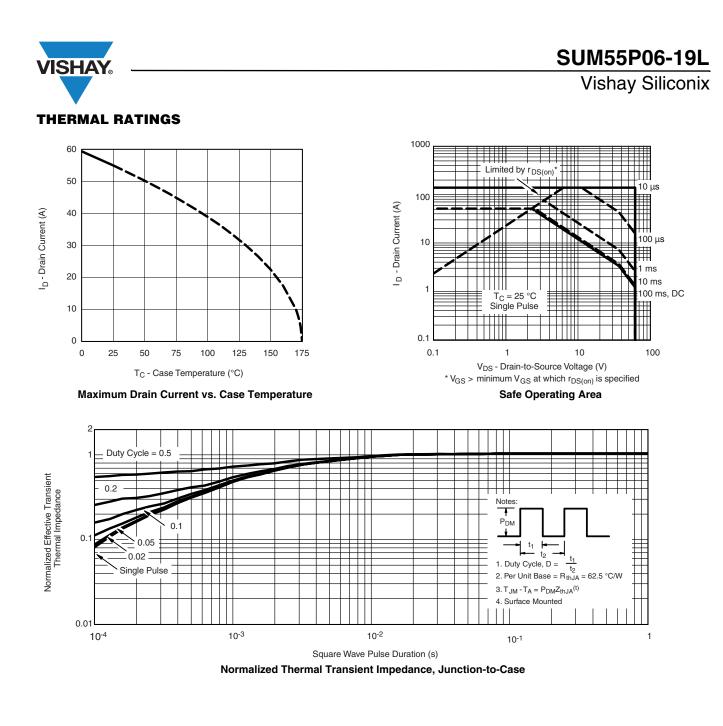
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs.Junction Temperature

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Vishay Siliconix

TO-263 (D²PAK): 3-LEAD









DETAIL A (ROTATED 90°)



		INCHES		MILLIMETERS		
DIM.		MIN.	MAX.	MIN.	MAX.	
А		0.160	0.190	4.064	4.826	
	b	0.020	0.039	0.508	0.990	
	b1	0.020	0.035	0.508	0.889	
	b2	0.045	0.055	1.143	1.397	
с*	Thin lead	0.013	0.018	0.330	0.457	
	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
CI	Thick lead	0.023	0.027	0.584	0.685	
	c2	0.045	0.055	1.143	1.397	
	D	0.340	0.380	8.636	9.652	
	D1	0.220	0.240	5.588	6.096	
D2		0.038	0.042	0.965	1.067	
D3		0.045	0.055	1.143	1.397	
D4		0.044	0.052	1.118	1.321	
	E	0.380	0.410	9.652	10.414	
	E1	0.245	-	6.223	-	
	E2	0.355	0.375	9.017	9.525	
E3		0.072	0.078	1.829	1.981	
	е	0.100	00 BSC 2.54 BSC		BSC	
	К	0.045	0.055	1.143	1.397	
L		0.575	0.625	14.605	15.875	
L1		0.090	0.110	2.286	2.794	
L2		0.040	0.055	1.016	1.397	
	L3	0.050	0.070	1.270	1.778	
	L4	0.010 BSC 0.254		BSC		
	М	-	0.002	-	0.050	
ECN: T13-0707-Rev. K, 30-Sep-13 DWG: 5843						

Notes

- 1. Plane B includes maximum features of heat sink tab and plastic. 2. No more than 25 % of L1 can fall above seating plane by
- max. 8 mils.3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB.
 - Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

This feature is for thick lead.

Revison: 30-Sep-13



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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